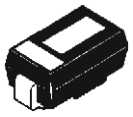
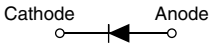
Schottky Rectifier, 1.0 A



SMA



FEATURES

- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Lead (Pb)-free ("PbF" suffix)
- Designed and qualified for industrial level

RoHS COMPLIANT

PRODUCT SUMMARY	
$I_{F(AV)}$	1.0 A
V_R	40 V
I_{RM}	26 mA at 125 °C

DESCRIPTION

The MBRA140TRPbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and very small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	1.0	A
V_{RRM}		40	V
I_{FSM}	t_p = 5 µs sine	120	A
V_F	1.0 Apk, T_J = 125 °C	0.49	V
T_J	Range	- 55 to 150	°C

VOLTAGE RATINGS			
PARAMETER	SYMBOL	MBRA140TRPbF	UNITS
Maximum DC reverse voltage	V_R	40	V
Maximum working peak reverse voltage	V_{RWM}		

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current See fig. 4	$I_{F(AV)}$	50 % duty cycle at T_L = 118 °C, rectangular waveform On PC board 9 mm^2 island (0.013 mm thick copper pad area)		1.0	A
Maximum peak one cycle non-repetitive surge current See fig. 6	I_{FSM}	5 µs sine or 3 µs rect. pulse	Following any rated load condition and with rated V_{RRM} applied	120	
		10 ms sine or 6 ms rect. pulse		30	
Non-repetitive avalanche energy	E_{AS}	T_J = 25 °C, I_{AS} = 1 A, L = 6 mH		3.0	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 µs Frequency limited by T_J maximum V_A = 1.5 x V_R typical		1.0	A

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	V_{FM} (1)	1 A	T_J = 25 °C	0.55	V
		2 A		0.71	
		1 A	T_J = 100 °C	0.5	
		2 A		0.65	
		1 A	T_J = 125 °C	0.49	
		2 A		0.63	
Maximum reverse leakage current See fig. 2	I_{RM} (1)	T_J = 25 °C	V_R = Rated V_R	0.5	mA
		T_J = 100 °C		10	
		T_J = 125 °C		26	
Threshold voltage	$V_{F(TO)}$	T_J = T_J maximum		0.36	V
Forward slope resistance	r_t			104	mΩ
Typical junction capacitance	C_T	V_R = 10 V_{DC}, T_J = 25 °C, test signal = 1 MHz		38	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		2.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/µs

Note

(1) Pulse width < 300 µs, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J (1), T_{Stg}		- 55 to 150	°C
Maximum thermal resistance, junction to lead	R_{thJL} (2)	DC operation See fig. 4	35	°C/W
Maximum thermal resistance, junction to ambient	R_{thJA}		80	
Approximate weight			0.07	g
			0.002	oz.
Device marking		Case style SMA (similar D-64)	V14	

Notes

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB, thermal probe connected to lead 2 mm from package

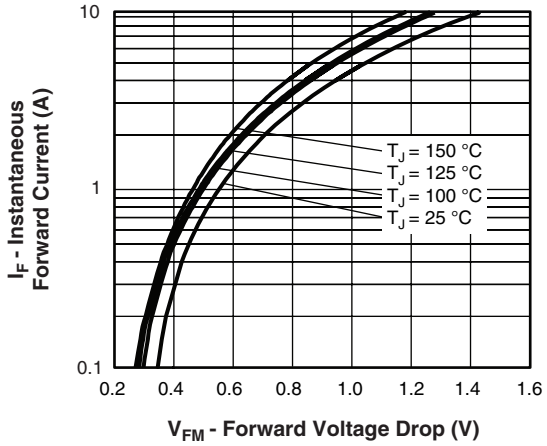


Fig. 1 - Maximum Forward Voltage Drop Characteristics

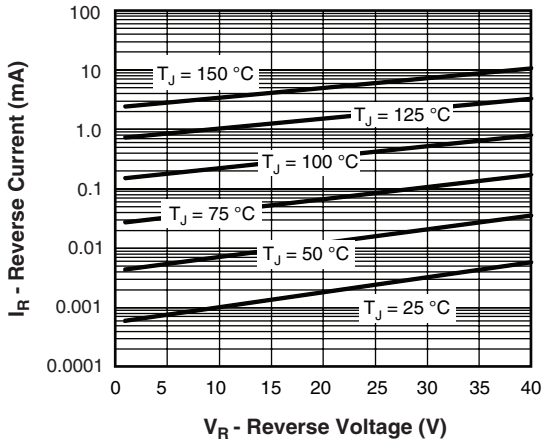


Fig. 2 - Typical Peak Reverse Current vs. Reverse Voltage

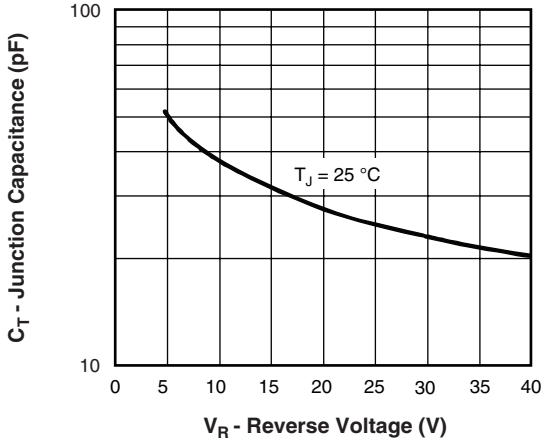


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

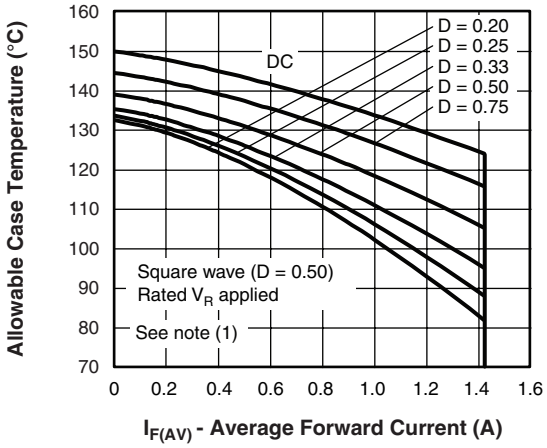


Fig. 4 - Maximum Average Forward Current vs. Allowable Lead Temperature

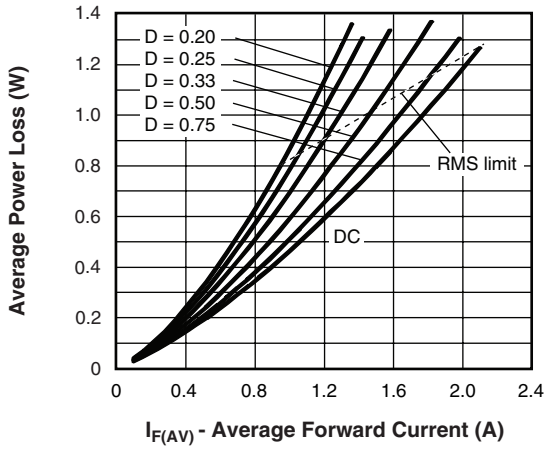


Fig. 5 - Maximum Average Forward Dissipation vs. Average Forward Current

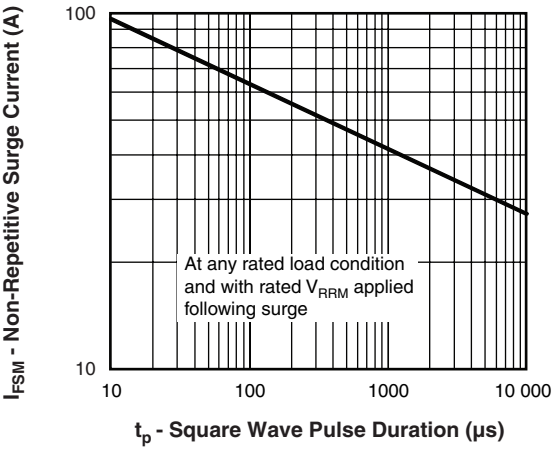


Fig. 6 - Maximum Peak Surge Forward Current vs. Pulse Duration

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 6); Pd_{REV} = Inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = 80 % rated V_R

ORDERING INFORMATION TABLE

Device code

MBR	A	1	40	TR	PbF
1	2	3	4	5	6

- 1 - Schottky MBR series
- 2 - A = SMA
- 3 - Current rating (1 = 1 A)
- 4 - Voltage rating (40 = 40 V)
- 5 - TR = Tape and reel (7500 pieces)
- 6 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95018
Part marking information	http://www.vishay.com/doc?95029
Packaging information	http://www.vishay.com/doc?95034

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